









Bundesministerium für Bildung und Forschung

GEFÖRDERT VOM



# An ultra-light vertex detector for the CBM Experiment

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# Physics goals of CBM



## Open charm reconstruction: The challenge



M. Deveaux

# **Open charm reconstruction: Concept**



# Requirements vs. detector performances (2003)



	Required	Hybrid pixels	CCD
Single point res. [µm]	~ 5	~ 30	~ 5
Material budget [X <sub>0</sub> ]	~ 0.3%	~ 1%	~ 0.1%
Time resolution [µs]	few 10	0.025	~100
Rad. hardness [n/cm <sup>2</sup> ]	> 10 <sup>13</sup>	>> 10 <sup>14</sup>	<< 10 <sup>10</sup>

# CMOS Monolithic Active Pixel Sensors (MAPS)

## Time resolution and rad. tolerance need improvement => Perform R&D



	Required	Hybrid pixels	CCD	MAPS (2003)
Single point res. [µm]	~ 5	~ 30	~ 5	3.5
Material budget [X <sub>0</sub> ]	~ 0.3%	1%	~0.1%*	~0.05%*
Time resolution [µs]	10-100	0.025	~100	>1000
Rad. hardness [n/cm <sup>2</sup> ]	> 10 <sup>13</sup>	>> 10 <sup>14</sup>	<< 10 <sup>10</sup>	> 10 <sup>12</sup>



Output: Cluster information (zero surpressed)

## **Radiation tolerance of MAPS**





# What about radiation hardness?

## *lonising radiation:*

- Energy deposited into the electron cloud
- May ionise atoms and destroy molecules
- Caused by charged particles and photons





Non-ionising radiation:

- Energy deposited into the crystal lattice
- Atoms get displaced
- Caused by heavy (fast leptons, hadrons) charged and neutral particles

Farnan I, HM Cho, WJ Weber, 2007. "Quantification of Actinide  $\alpha$ -Radiation Damage in Minerals and Ceramics." *Nature* 445(7124):190-193.

Sensor R&D: The operation principle





## Sensor R&D: Tolerance to non-ionising radiation



Key observation: Signal amplitude is reduced by bulk damage

## Sensor R&D: Tolerance to non-ionising radiation



Electric field increases the radiation hardness of the sensor Draw back: Need CMOS-processes with low doping epitaxial layer

# S/N of MIMOSA-18 AHR (high resistivity epi-layer)





Plausible conclusion: Radiation tolerance >10<sup>14</sup> n<sub>eq</sub>/cm<sup>2</sup> reached
Cooling required to operate heavily irradiated sensors

## Noise and cooling



Cooling is needed to exploid the improved radiation tolerance Alternative solution: Fast integration times help

# Random Telegraph Signal

Frequency and amplitude of RTS increase with temperature\*



#### Conclusion: RTS causes fake hits but cooling helps

## Radiation tolerance vs. pixel pitch



Non ionizing radiation tolerance depends strongly on pixel pitch Requirements of CBM are matched.

# Radiation tolerance of MAPS





# Sensor R&D: Tolerance to ionising radiation



Output: Cluster information (zero surpressed)

Imagers (0.35µm):

Tolerate 1-2 MRad if cooled.

Fast pixels are so far vulnerable:

- More transistors
- No space for radiation tolerant layout in 0.35µm CMOS.

 $\Rightarrow$  Current tolerance: 0.5 MRad

Progresses with 0.18 µm CMOS process ⇒ Seems radiation tolerant to 10 Mrad ⇒ Results shown by Marc Winter were confirmed

## **Tolerance to ionising radiation - Annealing**



Ionizing radiation increases leakage current of diodes Annealing alleviates ionizing radiation damage substantially No indication for reverse annealing => Recover detector on the fly(?)

# Just opening a bracked



## Separation of ionizing and non-ionizing doses

Reactor neutrons are polluted with parasitic gamma rays. Does this have an impact on the measurements?



## Effect of gamma rays is reduced due to annealing. Apparently, reactor neutrons dominated.



# Performances of MAPS (2013)



All requirements demonstrated with dedicated sensors.

Next step: Do it with ONE sensor

#### Remaining issues:

- Factor 2-3 in readout speed
- Extend internal bandwidth by factor of 5
- $\Rightarrow$  In reach of 0.18 µm CMOS technology

	Required	Hybrid pixels	CCD	MAPS** (2013)
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Material budget [X <sub>0</sub> ]	~ 0.3%	1%	~0.1%*	~0.05%*
Time resolution [µs]	few 10	0.025	~100	32
Rad. hardness [n/cm <sup>2</sup> ]	> 10 <sup>13</sup>	>> 10 <sup>14</sup>	<< 10 <sup>10</sup>	> 3x10 <sup>14</sup>

\*\* Best of specialized sensors \*Sensor only

# System integration – An MVD for CBM

Aim for thickness of 0.3%  $X_0$  (=0.3 mm Si equivalent)

## How to fix the sensors?





CBM-MAPS consume <1W/cm<sup>2</sup>

How to bias? How to evacuate heat? ...

...without material ... in vacuum?

## Integration of the sensors

The integration challenge:

# Integrate 50µm thick and bended silicon foils on a diamond support





# Naïve approach for system integration

Again, this structure will be fixed with

the novel Anti Gravitation Glue™.





## Integration concept of the MVD



Geometry of MVD-stations

Outside acceptance

Vacuum operation requires light and actively cooled device.

- Use cooling support from diamond to move heat out of acceptance
- Put heat sink and FEE outside acceptance

# Integration concept of the MVD



## Validation of the cooling concept

## Aim: Validate the cooling concept with TPG



## Observation:

- Temperature gradient on the station appears acceptable
- A 150 µm CVD diamond support might be sufficient for station 1
- Diamond => liquid heat transport needs optimization

Vacuum compatible cooling concept for 1W/cm<sup>2</sup> seems robust.

# The CBM-MVD prototype

\*) CVD and AI with cut-outs were tested for the reference plandes of the telescope. The prototype bases on a 100% filled CVD layer.

CVD<sup>\*</sup>

AI<sup>\*</sup>

BONDEDDDDD Chia MES-3 - Pin Mes Problecan











## Prototype: Beam test setup



Ambitioned performances:

- Up to 10 MIMOSA-26 running @10k frames/s, 3.5µm resolution.
- Free-running, scalable DAQ based on HADES TRB 100 MB/s.
- Actively cooled prototype (<0.3% X<sub>0</sub>)
- Passively cooled telescope arms (0.05% X<sub>0</sub>)

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## Some first results



Result so far for the DUT:

 $σ_x$ = 3.3 μm  $σ_y$ = 3.7 μm

## All performance plots very promising, analysis is being continued

# Stability of the readout



# Summary

## The CBM-Experiment

- CBM will be a heavy ion experiment located at FAIR
- The MVD bases on CMOS-MAPS (CPS) and is to measure open charm particles

Integration concept for the CBM-Micro Vertex Detector:

- Host MAPS on a vacuum compatible diamond cooling support
- Readout with ultra thin flex print cables
- Build local DAQ based on HADES TRB

## Results of prototyping:

- Handling of sensors successful (close to 100% yield)
- Readout system operated stable at highest rates applied
- Preliminary results compatible with IPHC-results

## Next steps:

- Demonstrate vacuum operation
- Prepare TDR